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Electra House, 32 Southtown Road Great Yarmouth, Norfolk NR31 0DU, England Telephone +44 (0)1493 602602 Email:sales@midasdisplays.com www.midasdisplays.com

MDT0660AIH-LVDS	1440 x 240	LVDS Interface	TFT Module
		Specification	
Version: 1		Date: 01/06/2018	
		Revision	
1	30/05/2018	First issue	

Display F	Display Features					
Display Size	6.60"					
Resolution	1440 x 240					
Orientation	Landscape					
Appearance	RGB					
Logic Voltage	3.3V		L'LIC			
Interface	LVDS	IWR	oHS ompliant			
Brightness	1000 cd/m ²	/ V 30	moliont			
Touchscreen		1 00	mphani			
Module Size	1 <mark>78</mark> .40 x 40.00 x 3.35 <mark>m</mark> m					
Operating Temperature	-30°C ~ +85°C					
Pinout	40 way FFC	Box Quantity	Weight / Display			
Pitch		ira - sili	nnlv			

* - For full design functionality, please use this specification in conjunction with the SSD1305Z specification.(Provided Separately)

Display Accessories					
Part Number	Description				
MPBV6	40 Way FFC to cable and wires. Driven by any driver board that can be wired to a 1mm pitch SHDR-40V-S-B receptacle.				
MCIB14/16	HDMI-to-LVDS interface board, with voltage generation.				

Optional Variants					
Appearances	Voltage				

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silico n TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 6.6 " TFT-LCD contains 1440x240 pixels, and can display up to 16.7M colors.

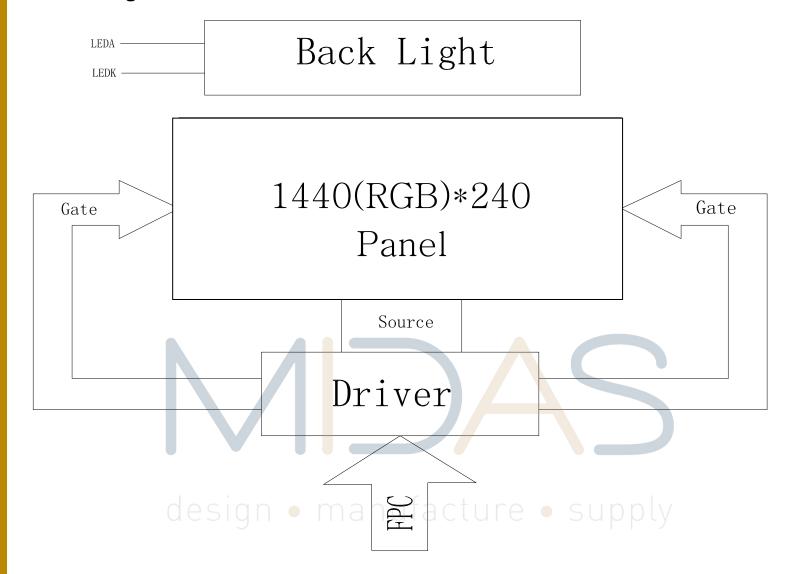
* Features

General Information	Specification	Hair Nara
Items	Main Panel	Unit Note
Display area(AA)	164.16(H)*27.36(V) (6.6 inch)	mm
Driver element	TFT active matrix	-
Display colors	262K/16.7M	colors
Number of pixels	1440(RGB)*240	dots
Pixel arrangement	RGB vertical stripe	
Pixel pitch	0.114(H)*0.114(V)	mm
Viewing angle	Free	o'clock
Controller IC	2*HX8249+HX8678	-
LCM Interface	6/8Bit LVDS	_
Display mode	Transmissive /Normally Black	-
Operating temperature	n • m a-30~+85 a cture	• squpply
Storage temperature	-40∼ + 90	C

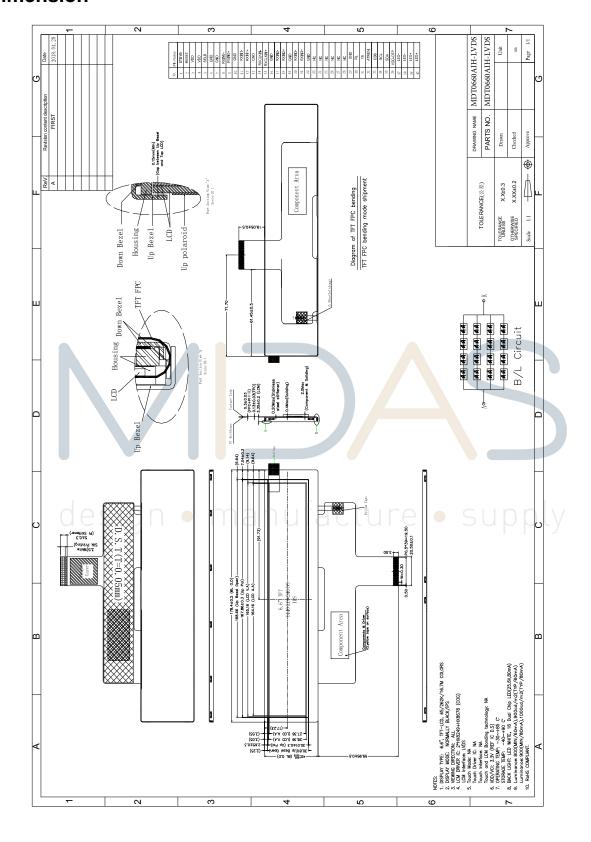
* Mechanical Information

	Item	Min.	Тур.	Max.	Unit	Note
NAI I -	Horizontal(H)	-	178.4	-	mm	
Module size	Vertical(V)	-	40	-	mm	
	Depth(D)	-	3.35	-	mm	
	Weight	-	TBD	-	g	

1. Block Diagram



Outline dimension



Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O		
1	STBYB	Enale IC	Note 1		
2	Reset	Reset IC			
3	VDD	Digital power-3.3v	Р		
4	VDD	Digital power-3.3v	Р		
5	SELB	6bit/8bit mode select	Note 3		
6	GND	Ground	Р		
7	GND	Ground	Р		
8	RXINO-	Negative LVDS differential data input	I		
9	RXINO+	Positive LVDS differential data input	I		
10	GND	Ground	Р		
11	RXIN1-	Negative LVDS differential data input	I		
12	RXIN1+	Positive LVDS differential data input	I		
13	GND	Ground	Р		
14	RXCLKIN-	Negative LVDS differential data input	I		
15	RXCLKIN+	Positive LVDS differential data input	I		
16	GND	Ground	Р		
17	RXIN2-	Negative LVDS differential data input	I		
18	RXIN2+	Positive LVDS differential data input	I		
19	GND	Ground	Р		
20	RXIN3-	Negative LVDS differential data input	I		
21	RXIN3+	Positive LVDS differential data input			
22	GND	Ground			
23	NC	No connected			
24	NC	No connected			
25	NC	No connected			

26	NC	No connected	
27	NC	No connected	
28	NC	No connected	
29	GND	Ground	Р
30	RL	Horizontal shift direction	Note 4
31	ТВ	Vertical shift direction	Note 4
32	ATREN	ATREN should be kept H.	I
33	CSB	No connected	-
34	SCL	No connected	
35	SDA	No connected	-
36	VDD-OTP	7.5V for OTP program (No connected)	Р
37	LED-	LED Cathode	Р
38	LED-	LED Cathode	Р
39	LED+	LED Anode	Р
40	LED+	LED Anode	Р

Note.1

STBYB=H(3.3V),normal operarion.

STBYB=L(GND),timing controller,source driver will rurn off,all opout are High-Z.

Note.2

Suggest to connection with an RC reset circuit for stability, Normally pull high.

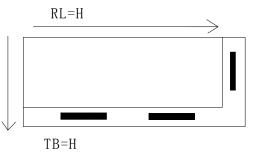
(47KΩ+0.1uF or extirnal MCU control)

Note.3

If LVDS iput data is 8 bit, SELB must be set to hight.

Note.4

Scan control Input		6
RL	ТВ	Scanning direcrion
VDD	VDD	Up to Down,Left to Right
GND	VDD	Up to Down,Right to left
VDD	GND	Down to Up,Left to Right
GND	GND	Down to Up,Right to left.



LCD Optical Characteristics

1. Optical specification

Item		Symbol	Condition	Min.	Тур.	Max.	Unit.	Note
Contrast R	Contrast Ratio		Θ=0	600	800			
Response time	Rising Falling	T _{R+} T _F	Normal viewing angle	-1	25	1	msec	
Uniformi	ty	S(%)		1	(60)	1	%	
		Wx		0.271	0.311	0.351		
	White	WY		0.293	0.333	0.373		
		Rx		0.552	0.592	0.632		
Color Filter	Red	Ry		0.287	0.327	0.367		
Chromacicity		Gx		0.319	0.359	0.399		
	Green	Gy		0.553	0.593	0.633		
		Bx		0.108	0.148	0.188		
	Blue	By		0.061	0.101	0.141		
		ΘL			80	I		
	Hor.	ΘR			80			
Viewing angle	d e s i Ver.	ΘU •	manufa	ctur	80 S	uppl	\vee	
	Ver.	ΘD			80)	
Option View D	irection			Free				

Electrical Characteristics

1. Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit	Note
Digital Supply Voltage	VDD	-0.3	4.0	V	Note1
Operating temperature	Тор	-30	+85	°C	
Storage temperature	T _{ST}	-40	+90	°C	

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

2. DC Electrical Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Digital Supply Voltage	vpp a	n 27 a	c t ^{3.3} ne	3.6	up y ly	
Normal mode Current	IDD		75		mA	
Lovel input veltere	VIH	0.7*VDD		VDD+0.3	V	
Level input voltage	VIL	GND-0.3		0.3*VDD	V	
Level output voltage	Vон	VDD-0.4			V	
	V _{OL}	GND		GND+0.4	V	

3. LED Backlight Characteristics

The back-light system is edge-lighting type with 32 chips LED

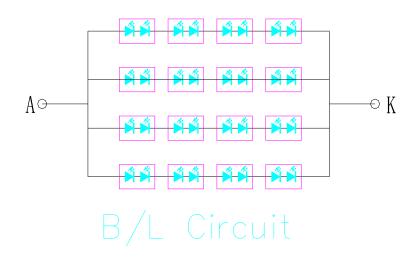
Item	Symbol	Min.	Тур.	Max.	Unit	Note
Forward Current	lF	60	80		mA	
Forward Voltage	VF		25.6		V	
LCM Luminance	1.\/	900	000		cd/m2	Note3
(I _F =60mA)	LV	800	900		CU/IIIZ	inotes
LCM Luminance	LV	900	1000		cd/m2	Note3
(I _F =80mA)	LV	900	1000		Cu/IIIZ	Notes
LED life time	Hr		50000		Hour	Note1,2
Uniformity	Avg	80			%	Note3

Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

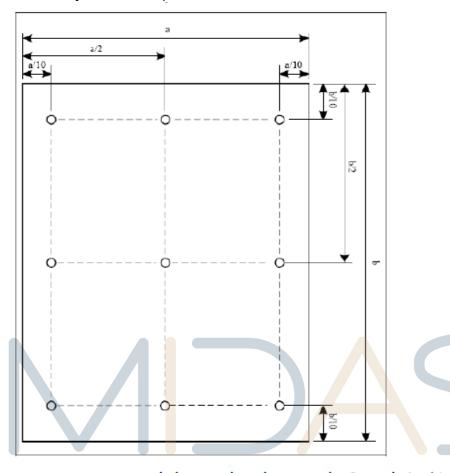
Ta=25±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at

Ta=25°C and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA. The constant current driving method is suggested.



Note (3) Luminance Uniformity of these 9 points is defined as below:



Uniformity = minimum luminance in 9 points (1-9)
maximum luminance in 9 points (1-9)

 $Luminance = \frac{Total\ Luminance\ of\ 9\ points}{9}$

AC Characteristics

1. LVDS 6-bit vs. 8-bit mode

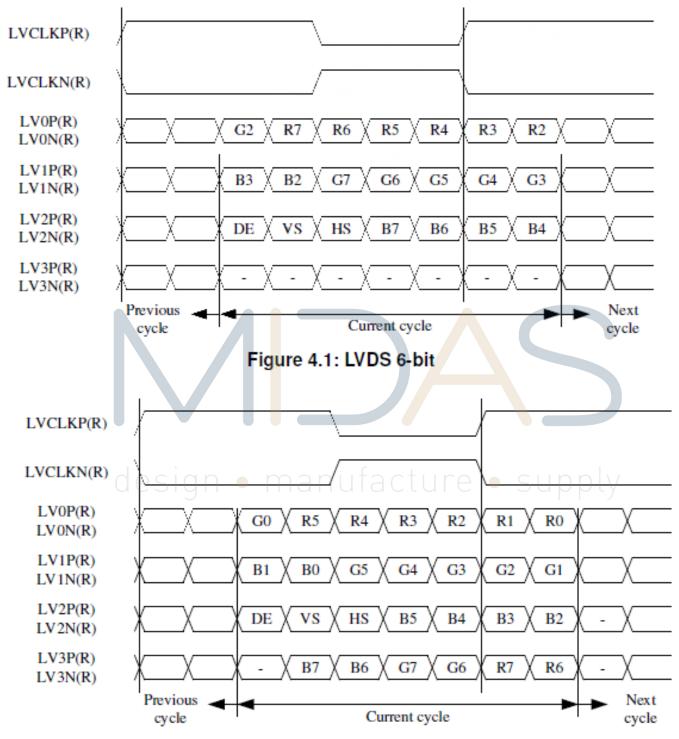
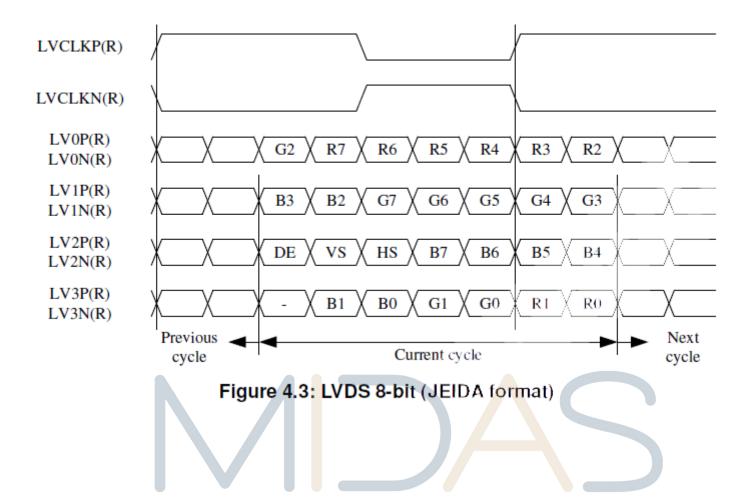


Figure 4.2: LVDS 8-bit (VESA format)



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2. LVDS input timing

LVDS input timing is described as below.

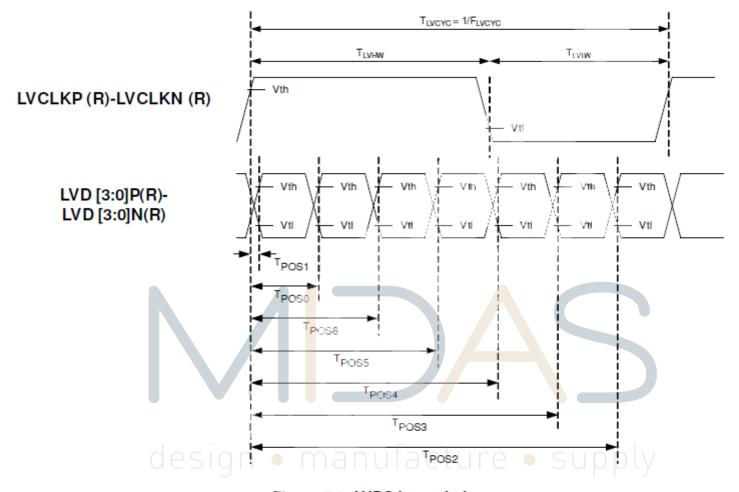


Figure 7.2: LVDS input timing

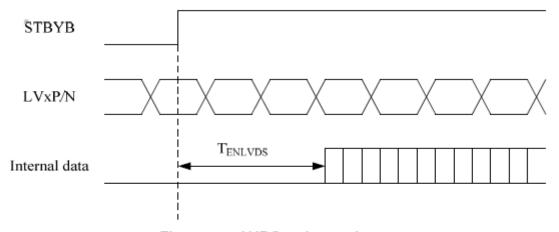
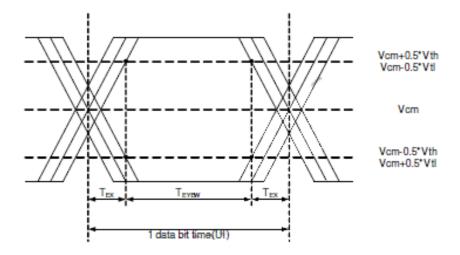


Figure 7.3: LVDS wake up time

Single-ended: LVD [3:0]P, LVD [3:0]N



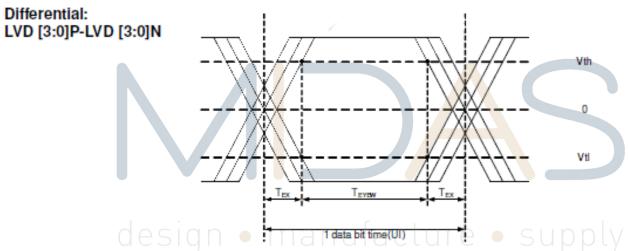


Figure 7.4: LVDS input eye diagram

Parameter	Symbol		Spec.		
raianetei	- Symbol	Min.	Typ.	Max.	Unit
Clock frequency	FLVCYC	10	-	85	MHz
Clock period	TLVCYC	11.76	-	100	nsec
1 data bit time	UI	•	1/7	-	TLVCYC
Clock high time	LVHW	2.9	4	4.1	UI
Clock low time	LVLW	2.9	3	4.1	UI
Position 1	TPOS1	-0.2	0	0.2	UI
Position 0	TPOS0	0.8	1	1.2	UI
Position 6	TPOS6	1.8	2	2.2	UI
Position 5	TPOS5	2.8	3	3.2	UI
Position 4	TPOS4	3.8	4	4.2	UI
Position 3	TPOS3	4.8	5	5.2	UI
Position 2	TPOS2	5.8	6	6.2	UI
Input eye width	TEYEW	0.6	-	-	UI
Input eye border	TEX	-	-	0.2	UI
LVDS wake up time	TENLVDS		-	150	μs

Table 7.2: LVDS input timing parameters

3. Reset timing

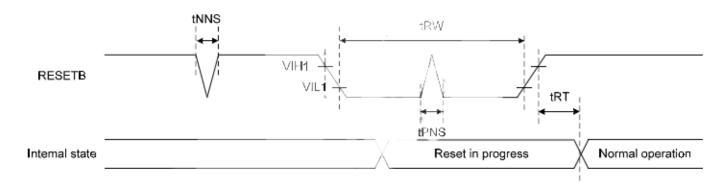


Figure 7.5: Reset timing

(VDD1=VDD2=2.7 to 3.6V, GND=0V, TA=-40 to +95 °C)

Cianal	Baramatar	Symbol Spec.		Spec.		Unit
Signal	Parameter	Symbol	Min.	Тур.	Max.	Unit
	Reset pulse width	tRW	10	-	-	μs
DECETO	Reset complete time	tRT	-	-	5	μs
RESETB	Positive spike noise width	tPNS	-	-	100	ns
	Negative spike noise width	tNNS	-	-	100	ns

Table 7.4: Reset timing parameters

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LCD Module Out-Going Quality Level

1. VISUAL & FUNCTION INSPECTION STANDARD

1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

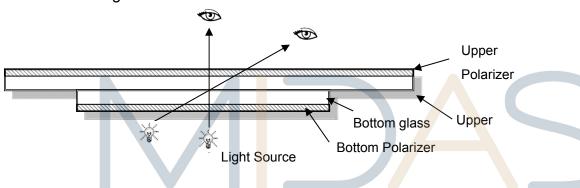
Temperature : 25±5 °C

Humidity: 65%±10%RH

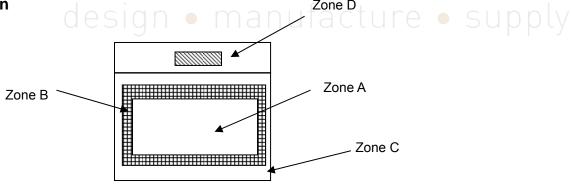
Viewing Angle: Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm







Zone A: Effective Viewing Area(Character or Digit can be seen)

Zone B: Viewing Area except Zone A

Zone C: Outside (Zone A+Zone B) which can not be seen after assembly by customer.)

Zone D: IC Bonding Area

Note:As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

1.3 Sampling Plan

According to GB/T 2828.1-2003 ; , normal inspection, Class $\,\,{\rm II}\,\,$ AQL:

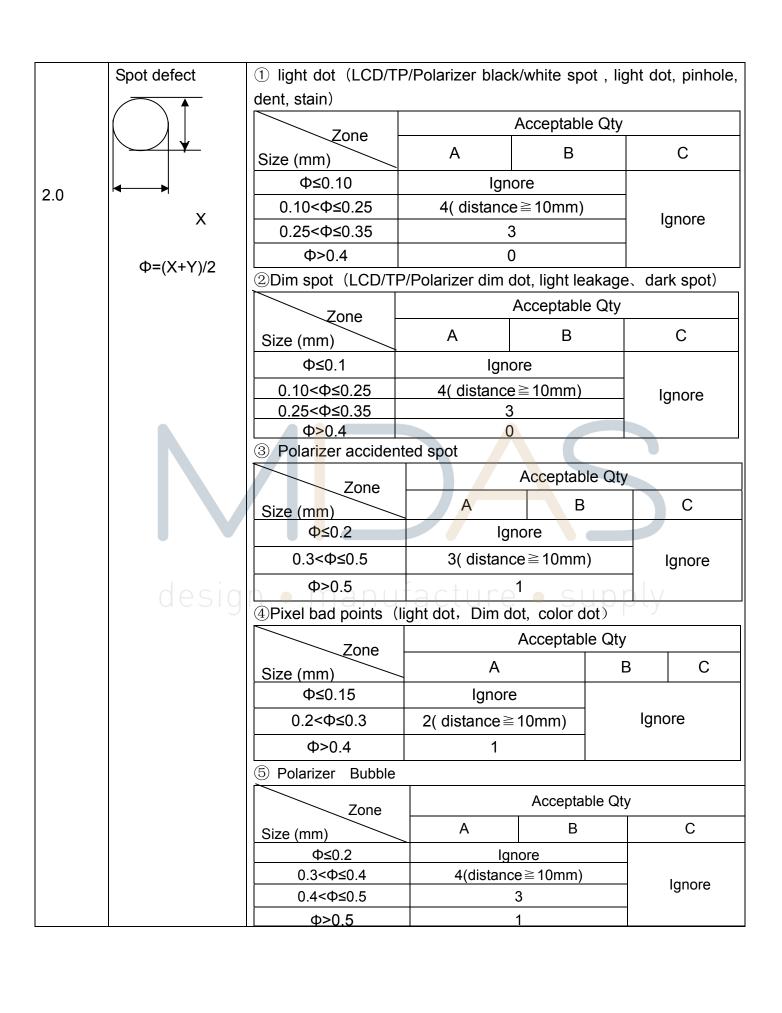
Major defect	Minor defect		
0.65	1.5		

LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
		1) No display, Open or miss line	
1	Functional defects	2) Display abnormally, Short	
'	i unclional defects	3) Backlight no lighting, abnormal lighting.	
		4) TP no function	Major
2	Missing	Missing component	
		Overall outline dimension beyond the drawing	
3	Outline dimension	is not allowed	
4	Color tone	Color unevenness, refer to limited sample	
		Light dot, Dim spot,Polarizer Bubble;	
5	Spot Line defect	Polarizer accidented spot.	Minor
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

1.4 Criteria (Visual)

Number	Items		Criteria(mm)	
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height	(1) The edge of LCD broken			
L: Length of ITO,		X	Υ	Z
T: Height of LCD		≤3.0mm	<pre><inner border="" line="" of="" pre="" seal<="" the=""></inner></pre>	≤T
	(2)LCD corner broken X Y ≤3.0mm ≤L			
(3) LCD crack		TIUIDUL .	Crack Not allowed	rty



			Length(m	Acce	ptable Q	tv	7
	Line defect	Width(mm)	m)	A	В	С	-
2.0	(LCD/TP	Ф≤0.05	Ignore	Ignore			
3.0	/Polarizer backlight black/white line,	0.05 <w≤0.06< td=""><td>L≤5.0</td><td>N≤3</td><td></td><td>Ignore</td><td></td></w≤0.06<>	L≤5.0	N≤3		Ignore	
	scratch, stain)	0.07 <w≤0.08< td=""><td>L≤4.0</td><td>N≤2</td><td></td><td></td><td></td></w≤0.08<>	L≤4.0	N≤2			
		0.08 <w< td=""><td></td><td>Define as spot</td><td>defect</td><td></td><td></td></w<>		Define as spot	defect		
4.0	Electronic Comp onents SMT	Not allow missing parts, solderless connection, cold solder joint, mis match, The positive and negative polarity opposite					mis
5.0	Display color& B rightness	 Color: Measuring the color coordinates, The measurement standar d according to the datasheet or samples. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples. 					
6.0	LCD Mura	By 5% ND filter invisible.					

	desi	TP film	Size Φ(mm)	ure	Acceptable	Qty		
7.0	7.0 RTP Related		Φ≤0.1 0.1<Φ≤0.25 0.25<Φ≤0.35 Φ>0.4	A B Ignore 4 (distance ≥ 10mm) 3 1			C	
		TP film scratch	Width(mm) Φ≤0.05 0.05 <w≤0.06 0.07<w≤0.08="" 0.08<w<="" td=""><td>Length(mm) Ignore L≤5.0 L≤4.0</td><td>Acce A Ignore N≤3 N≤2 Define as spo</td><td></td><td>C Ignore</td></w≤0.06>	Length(mm) Ignore L≤5.0 L≤4.0	Acce A Ignore N≤3 N≤2 Define as spo		C Ignore	

	Assembly deflection	beyond the edge of backlight ≤0.2mm
	Bulge (undulation included)	The ITO film plumped below 0.40mm, it's ok.
		<0.4mm
		1規律性
	Newton Ring	Newton Ring area>1/3 TP area NG Newton Ring area≤1/3 TP area OK 2.非兒津生
desi	gn • m	nanufacture • supply wutton
	TP corner broken X: length	X Y Z Z <cover th="" thicknes<=""></cover>
	Y: width Z: height	*Circuitry broken is not allowed.

		X	Y	Z	X ₁
	TP edge broken	X≤4mm	Y≤2mm	Z <cover thickness</cover 	Z
X : length Y : width	X : length Y : width Z : height	* Circuitry b	roken is no	t allowed.	
riteria (functional items)					

			1
Number	Items	Criteria (mm)	
1	No display	Not allowed	
2	Missing segment	Not allowed	
3	Short	Not allowed	
4	Backlight no lighting	Not allowed	
5	TP no function	Not allowed	

Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	85°C,96H	
Low Temperature Operating	-30°C, 96HR	
High Temperature Storage	90°C, 96HR	Inspection after 2~4hours
Low Temperature Storage	-40°C, 96HR	storage at room temperature,
High Temperature & High	+60°C, 90% RH ,96 hours.	the sample shall be free from
Thermal Shock (Non-operation)	-30°C,30 min ↔ +85°C,30 min, Change time:5min 20CYC.	defects: 1.Air bubble in the LCD; 2.Non-display;
ESD test	Air:±8KV, 5times; Contact:±6KV, 5 times;	3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	than initial value.
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

- 1. The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance $> 10M\Omega$) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

Cautions and Handling Precautions

1. Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
- Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
- If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
- Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.
- (14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

2. Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
- It is highly recommended to store the module with temperature from 0 to 35 ℃ and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
- In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.